

Ad hoc announcement pursuant to Art. 53 LR.

Stock code: 300207

Securities abbreviation: Sunwoda

Ann No.:<Xin>2024-040

Sunwoda Electronic Co., Ltd.

**ANNOUNCEMENT ON PUBLIC ISSUANCE OF CORPORATE
BONDS TO PROFESSIONAL INVESTORS**

The board of directors of the Company and all of its directors hereby warrant the truthfulness, accuracy and completeness of the contents of this announcement, guarantee that there are no false representations, misleading statements or material omissions contained herein.

On 26 April 2020, Sunwoda Electronic Co., Ltd. (hereinafter referred to as “Sunwoda”) obtained the approval on the registration for the public issuance of corporate bonds in an aggregate par value up to RMB1 billion to professional investors (Zheng Jian Xu Ke [2020] No. 794) issued by the China Securities Regulatory Commission. The Company issued bonds in three tranches named by “2020 Corporate Bonds of Sunwoda Electronic Co., Ltd. Publicly Issued to Professional Investors (First Tranche) (Epidemic Prevention and Control Bonds), (Second Tranche) and (Third Tranche)”.

Overview of Corporate Bonds

Bond abbreviation	Bond code	Issue size (RMB100 million)	Issuance date	Maturity date	Bond status
20 Xin Wang 01	149157	3.90	2020-06-23	2023-06-23	Interest paid
20 Xin Wang 02	149218	2.10	2020-08-31	2023-08-31	Interest paid
20 Xin Wang	149219	4.00	2020-08-31	2025-08-31	Continue to

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In order to further broaden the financing channels of the Company, optimize the debt structure and reduce the financing costs, as approved by the sixth meeting of the sixth session of the Board of Directors and the sixth meeting of the sixth session of the Supervisory Committee of the Company, the Company agreed to initiate a new round of public issuance of corporate bonds to professional investors. The specific proposal of the public issuance of corporate bonds and related matters are explained as follows:

I. Description of the Company’s Qualification on Public Issuance of Corporate Bonds to Professional Investors

In accordance with the provisions and requirements of the Company Law of the People’s Republic of China, the Securities Law of the People’s Republic of China, the Measures for Administration of Issuance and Trading of Corporate Bonds (hereinafter referred to as the “Administrative Measures”) and other laws, regulations and regulatory documents, after comparing the actual situation with the abovementioned provisions of the relevant laws, regulations and regulatory documents on an item-by-item basis, the Company believes that the Company is in compliance with the current corporate bond policy and the various provisions of the conditions for the public offering of corporate bonds to professional investors, and is qualified for the public offering of corporate bonds to professional investors.

II. Overview of the Public Issuance of Corporate Bonds

(I) Type of securities

The type of securities to be issued in the public issuance is corporate bonds.

(II) Issue size

The Company intends to publicly issue corporate bonds with an aggregate par value up to RMB1.5 billion (inclusive) in one or more tranches to professional investors in the PRC. The specific issue size and tranches shall be submitted to the general meeting to authorize the board of directors of the Company (the “Board”) or the person(s) authorized by the Board and the lead underwriter to determine based on

the Company's capital requirements and the prevailing market condition at the time of issuance of corporate bonds.

(III) Par value and issue price

The corporate bonds in this public issuance will be issued at par value of RMB100 each.

(IV) Maturity and variety of bonds

The corporate bonds shall have a maturity of not more than 5 years (inclusive), and the corporate bonds may be of a single maturity variety or a mixture of multiple maturities. The specific variety and maturity composition of the corporate bonds shall be submitted to the general meeting to authorize the Board or the person(s) authorized by the Board to determine based on the Company's capital requirements and the prevailing market condition at the time of issuance.

(V) Coupe rate and method of determination

Coupe rate of the corporate bonds in the public issuance shall be submitted to the general meeting to authorize the Board or the person(s) authorized by the Board and the lead underwriter to determine based on the Company's capital requirements and the prevailing market condition at the time of issuance of corporate bonds.

(VI) Principal and interest repayment method

Interest is accruable on the corporate bonds in the public issuance annually on a simple but not compound basis. The interest is payable once annually and the principal thereof is payable at maturity in one lump sum. The last interest payment shall be made together with the principal payment.

(VII) Issuance method and issuance target

The issuance method shall be public offering and the issuance target shall be investors who meet the requirements of relevant laws and regulations.

(VIII) Use of proceeds

The proceeds from the corporate bonds will be used to finance project investment, repay interest-bearing debts, and supplement working capital and for other purposes in compliance with relevant laws and regulations. The specific use shall be submitted to the general meeting to authorize the Board or the person(s)

authorized by the Board to determine in accordance with the financial position of the Company.

(IX) Credit enhancement measures

Specific credit enhancement measures for corporate bonds in the public issuance shall be submitted to the general meeting to authorize the Board or the person(s) authorized by the Board to determine.

(X) Investor protection provisions

Specific investor protection provisions shall be submitted to the general meeting to authorize the Board or the person(s) authorized by the Board to formulate in compliance with relevant laws and regulations, and requirements of the stock exchange.

(XI) Validity of the resolution

The resolution in relation to the public issuance of corporate bonds at the Board meeting and the general meeting shall be valid within 36 months from the date of consideration and approval of the resolution.

III. Authorizations in Relation to Corporate Bonds in the Public Issuance

In order to effectively coordinate specific matters in the process of the public issuance of corporate bonds, the Company agrees to authorize the Board or the person(s) authorized by the Board at the general meeting, on the basis of the issuance proposal adopted at the general meeting, to handle all matters related to the public issuance, in line with the principle of maximizing the Company's interest, including but not limited to:

(I) In accordance with the national laws and regulations, relevant provisions of regulatory authorities and the resolutions adopted at the general meeting of the Company, and based on the actual situation of the Company and the bond market, to develop and adjust the specific issuance proposal for the corporate bonds, and revise and adjust the issuance terms of the corporate bonds, including but not limited to the specific issue size, term of bonds, bond variety, coupon rate and method of determination, the timing of issuance, the issue method (including whether to issue by tranches, and the quantity of issuance at each tranche), whether to set the terms of

resale and terms of redemption and the specific content of such terms, guarantee arrangements, the deadline and way of principal and interest repayment, use of proceeds, rating arrangements, guarantee arrangements for debt repayment (including but not limited to the guarantee measures for debt repayment under the proposal for the public issuance), specific subscription methods, specific placing arrangements, listing of the bonds and all matters related to the proposal for the public issuance;

(II) To make the decision to engage intermediary institutions to assist the Company in handling the matters related to the declaration and listing for the public issuance of corporate bonds;

(III) To select bond trustee(s) for the public issuance, sign bond trustee management agreement(s) and formulate rules for bondholders' meeting;

(IV) To prepare, approve, sign, modify and announce various legal documents related to the public issuance, and make appropriate supplement or adjustment to the declaration documents according to the requirements of regulatory authorities;

(V) Upon the completion of the public issuance, to handle the listing of the corporate bonds under the public issuance;

(VI) If there is any change to regulatory authorities' policies on the issuance of corporate bonds or the market conditions, to make corresponding adjustments to the matters related to the public issuance according to the opinions of regulatory authorities, except for the matters that must be re-voted at the general meeting according to relevant laws, regulations and the articles of association, or to decide whether to continue implementing the public issuance according to the actual situation; and

(VII) To handle other matters related to the public issuance.

It is proposed to authorize the Board of the Company at the general meeting and to approve the Board to authorize the chairman or other persons authorized by the chairman as the authorized person(s) of the public issuance to, on behalf of the Company, deal with the matters related to the public issuance according to the resolution of the general meeting and the authorization by the Board.

The foregoing authorization is valid from the date of consideration and approval

at the general meeting to the date when the abovementioned authorized matters are completed.”

IV. Opinion of Independent Directors’ Special Meeting

The current actual situation of the Company is in line with the prevailing policy on corporate bonds and the provisions of the conditions for public issuance to professional investors, and the Company has the qualifications and requirements for the public issuance of corporate bonds. The proposal for the public issuance of corporate bonds is reasonable and feasible, which is conducive to broadening financing channels, reducing the financing costs of the Company, and promoting the sustainable and healthy development of the Company, and is in line with the interests of the Company and all shareholders. It is agreed that the Company will promote the relevant work in accordance with the proposal for the issuance of corporate bonds and submit the relevant proposal for the public issuance of corporate bonds to the 2023 annual general meeting of the Company for consideration.

V. Documents Available for Inspection

1. Resolution of the sixth meeting of the sixth session of the Board of Directors.
2. Resolution of the sixth meeting of the sixth session of the Supervisory Committee.
3. Resolution of the sixth independent directors’ special meeting of the sixth session of the Board of Directors.

Notice is hereby given.

Sunwoda Electronic Co., Ltd.

Board of Directors

11 April 2024